

ABSTRACT



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An exposure apparatus for accurately and quickly transferring mask patterns to a substrate on which a plurality of pattern layers are formed, and a method of manufacturing microdevices that uses the exposure apparatus. A wafer mark (WM1) (or substitute wafer mark (WM1')) of a gate electrode layer (Lg) and a wafer mark (WM2) of a second interlayer insulating layer (Li2) are formed on a street line of a wafer (W). Mark bars WMnm (n=1, 2, M-1 to 4) of the wafer marks (WM1, WM2) are alternately arranged, and combined marks are formed. The combined marks are simultaneously detected with an alignment system, and positional information of the wafer marks (WM1, WM2) is computed based on the detection results. Then, the circuit patterns on a reticle are aligned with a shot region (SAn) on the wafer based on the computed positional information.



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